

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N04S4L-08A	**Issued**	27. April 2022
MA#	MA005739637		
Package	PG-TDSON-8-10	**Weight***	99.72 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.237	1.24	1.24	12404	12404
chip_2	inorganic material	silicon	7440-21-3	1.237	1.24	1.24	12404	12404
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		132	
	non noble metal	iron	7439-89-6	0.044	0.04		439	
	non noble metal	copper	7440-50-8	43.681	43.82	43.87	438034	438605
wire	non noble metal	aluminium	7429-90-5	0.828	0.83	0.83	8303	8303
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		905	
	plastics	epoxy resin	-	6.405	6.42		64232	
	inorganic material	silicondioxide	60676-86-0	38.612	38.72	45.23	387199	452336
leadfinish	non noble metal	tin	7440-31-5	1.396	1.40	1.40	14003	14003
plating	inorganic material	phosphorus	7723-14-0	0.001			14	
	non noble metal	nickel	7440-02-0	0.603	0.60	0.60	6048	6062
solder	non noble metal	tin	7440-31-5	0.057	0.06		576	
	noble metal	silver	7440-22-4	0.072	0.07		720	
	non noble metal	lead	7439-92-1	2.741	2.75	2.88	27488	28784
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.71	2.71	27064	27099
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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